

### •General Description

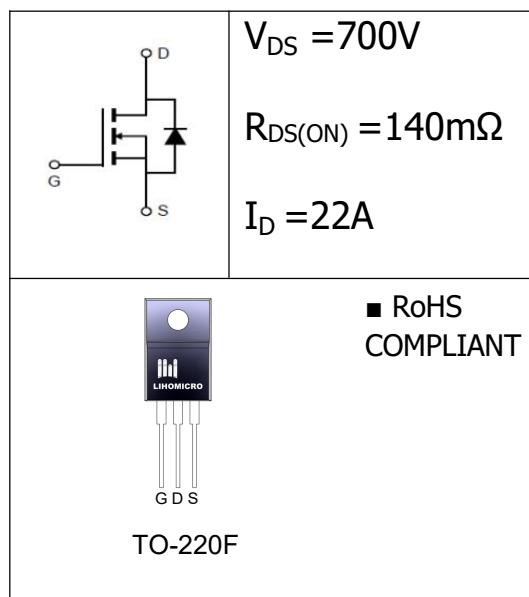
The SJ MOSFET LH70R140SFD has the low  $R_{DS(on)}$ , low gate charge, fast switching and excellent avalanche characteristics. This device offers extremely fast and robust body diode, and is suitable for telecom and power supplies.

### •Features

- Much lower  $R_{DS(ON)}$
- Much lower FOM for fast switching efficiency

### •Application

- Lighting
- Inverter System
- Power Supplies



### •Ordering Information:

Part number	LH70R140SFD		
Package	TO-220F		
Basic ordering unit (pcs)	1000		
Normal Package Material Ordering Code	LH70R140SFDF-T0220F-TU		
Halogen Free Ordering Code	LH70R140SFDF-T0220F-TU-HF		

### •Absolute Maximum Ratings (TC = 25°C)

PARAMETER	SYMBOL	Value	UNIT
Drain-Source Breakdown Voltage	$BV_{DSS}$	700	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current TC = 25°C TC = 100°C	$I_D$	22	A
		14	
Pulsed drain current (TC = 25°C, tp limited by Tjmax) <sup>1</sup>	$I_D$ pulse	66	A
Single Pulse Avalanche Energy <sup>1</sup>	$I_{AR}$	4.2	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	484	mJ
Repetitive Avalanche Energy <sup>1</sup>	$E_{AR}$	0.7	mJ
Power Dissipation(TC=25°C)	$P_D$	34	W
Operating Temperature and Storage Temperature Range	$T_J/T_{STG}$	-55~+150	°C
Reverse Diode dv/dt <sup>3</sup>	dv/dt	50	V/ns
Maximum Diode Commutation Speed <sup>3</sup>	di/dt	900	A/ns

**•Electronic Characteristics**

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	700	--	--	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	--	4.5	V
Drain-source On Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 7.5A$	--	0.12	0.14	$\Omega$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS} = 680V, V_{GS} = 0V, T_J = 25^\circ C$	--	--	1	uA
		$V_{DS} = 680V, V_{GS} = 0V, T_J = 125^\circ C$	--	--	100	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 30$	--	--	$\pm 100$	nA
Forward Transconductance <sup>3</sup>	$R_G$	f=1.0MHz open drain	--	--	12	$\Omega$
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 100V, f = 1.0MHz$	--	1834	--	pF
Output Capacitance	$C_{oss}$		--	57	--	
Reverse transfer Capacitance	$C_{rss}$		--	1.7	--	
Turn-on delay time	$T_{d(on)}$	$V_{DD} = 400V, I_D = 20A, R_G = 25\Omega$	--	34	--	nS
Rise time	$T_r$		--	72	--	
Turn -Off Delay Time	$T_{d(off)}$		--	114	--	
Fall time	$T_f$		--	41	--	
Total Gate Charge	$Q_g$	$I_D = 20A, V_{DS} = 520V, V_{GS} = 10V$	--	42	---	nC
Gate-to-Source Charge	$Q_{gs}$		--	10	--	
Gate-to-Drain Charge	$Q_{gd}$		--	17	---	
Continuous Diode Forward Current	$I_s$		--	--	22	A
Pulsed Diode Forward Current	$I_{SM}$		--	--	66	A
Diode Forward Voltage	$V_{SD}$	$T_J = 25^\circ C, I_s = 20A, V_{GS} = 0V$	--	0.9	1.2	V
Reverse Recovery Time	$t_{rr}$	$V_{RR} = 400V, I_f = I_s, dI_f/dt = 100A/\mu s$	--	112	--	ns
Reverse Recovery Charge	$Q_{rr}$		--	0.54	--	uC
Peak Reverse Recovery Current	$I_{RRM}$		--	9.6	--	A

**•Thermal Characteristics**

PARAMETER	SYMBOL	MAX		UNIT
Thermal Resistance Junction-case	$R_{thJC}$	3.7		$^\circ C/W$
Thermal Resistance Junction-ambient	$R_{thJA}$	80		$^\circ C/W$

Notes:

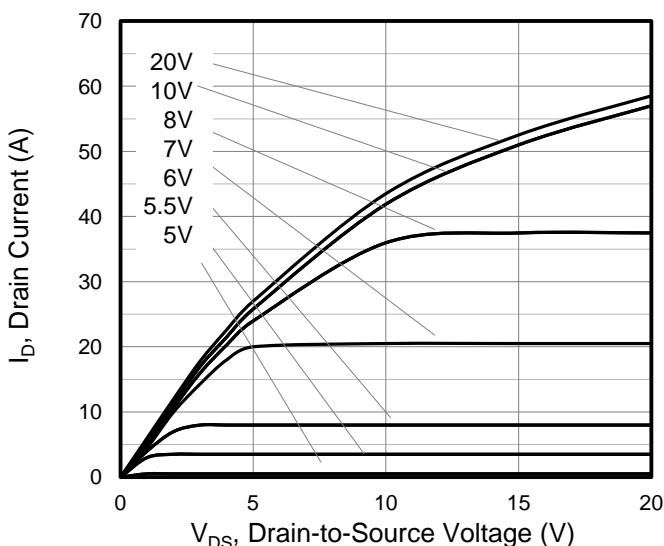
1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2.  $I_{AS} = 3.5A, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ C$

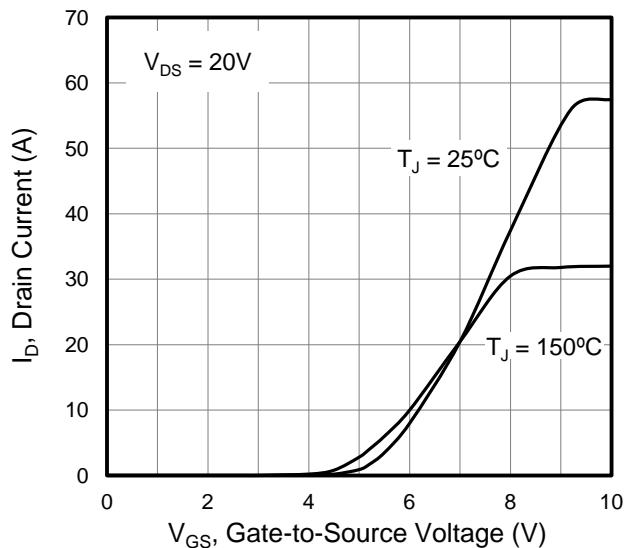
3. Pulse Test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$

- **Typical Characteristics**  $T_J=25^\circ\text{C}$ , unless otherwise noted

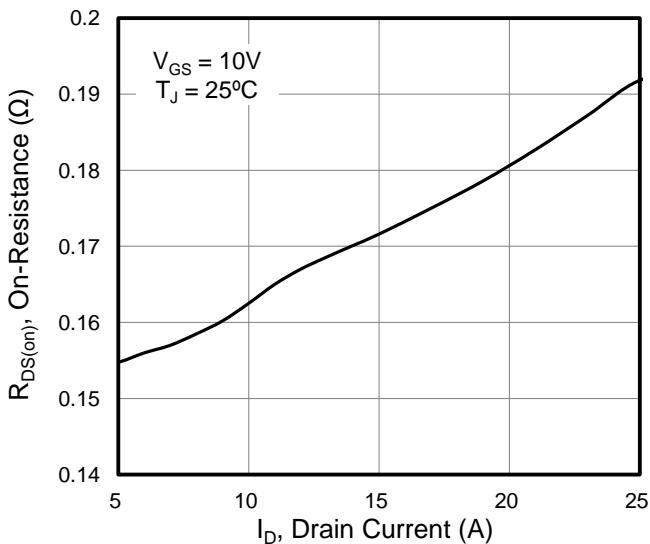
**Figure 1. Output Characteristics**



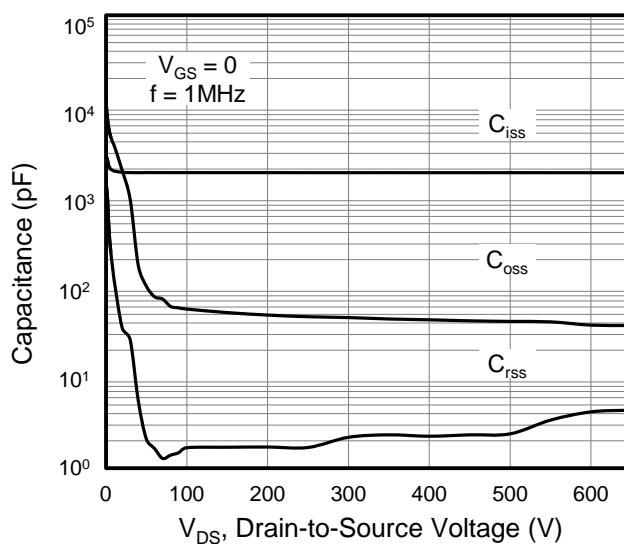
**Figure 2. Transfer Characteristics**



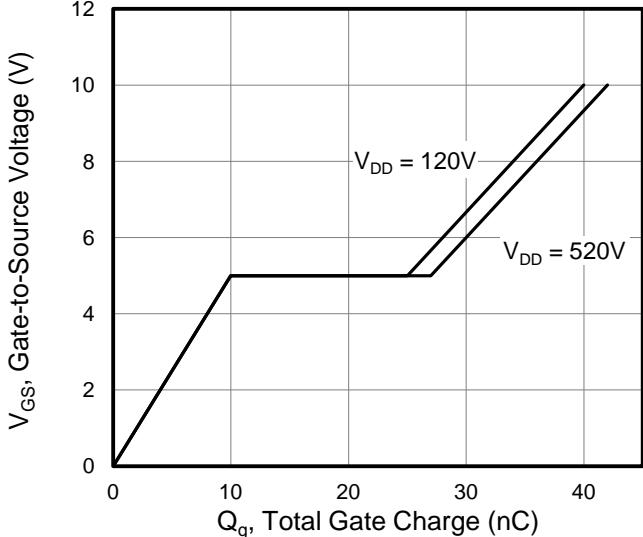
**Figure 3. On-Resistance vs. Drain Current**



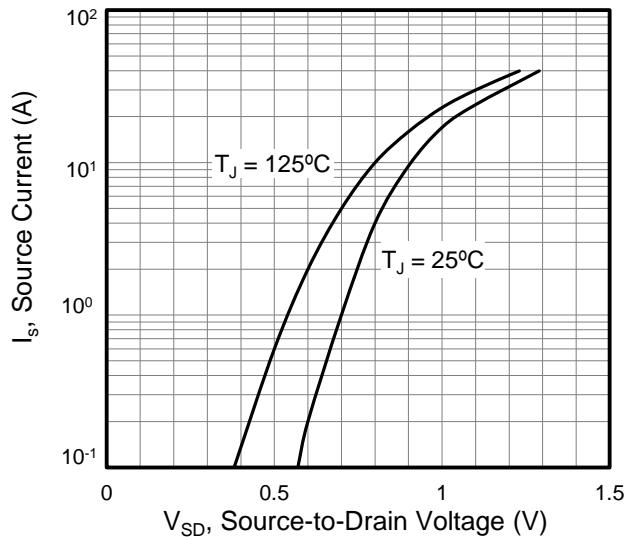
**Figure 4. Capacitance**

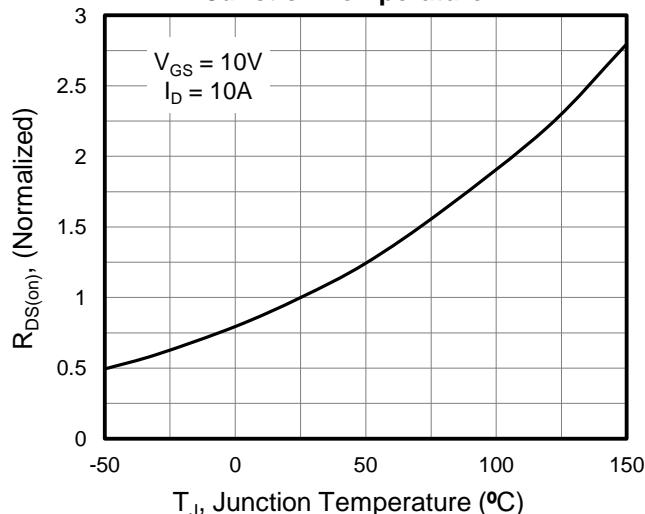
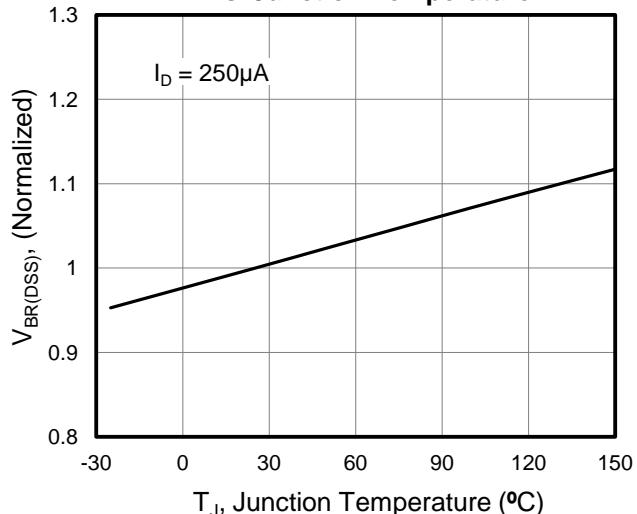
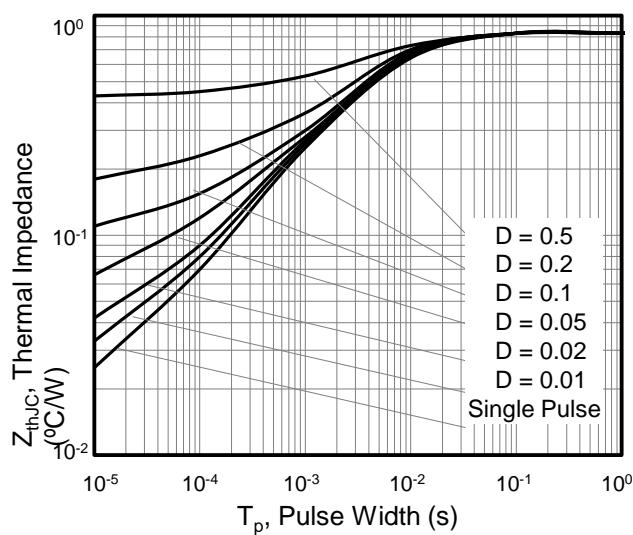
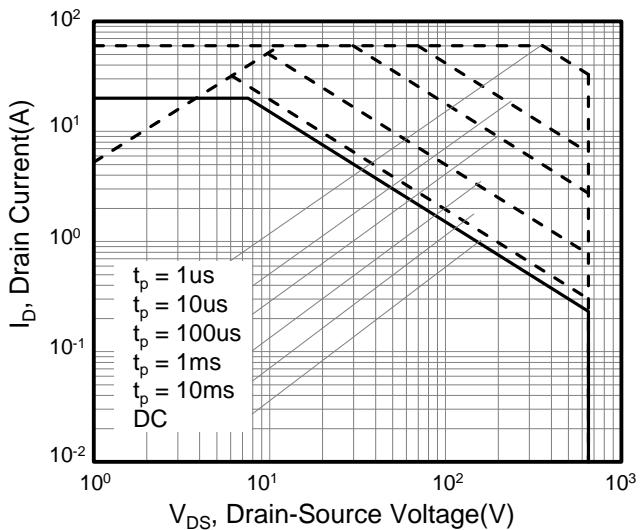


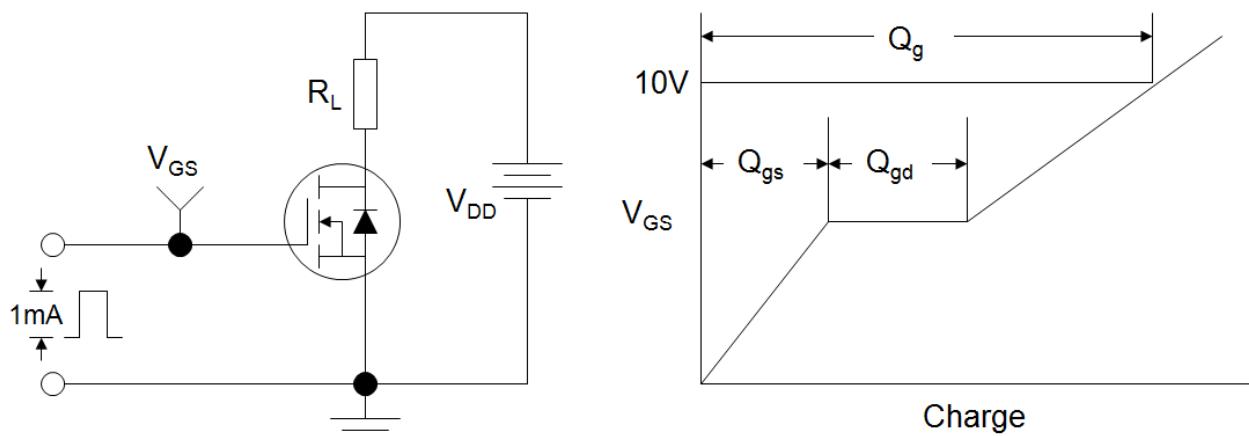
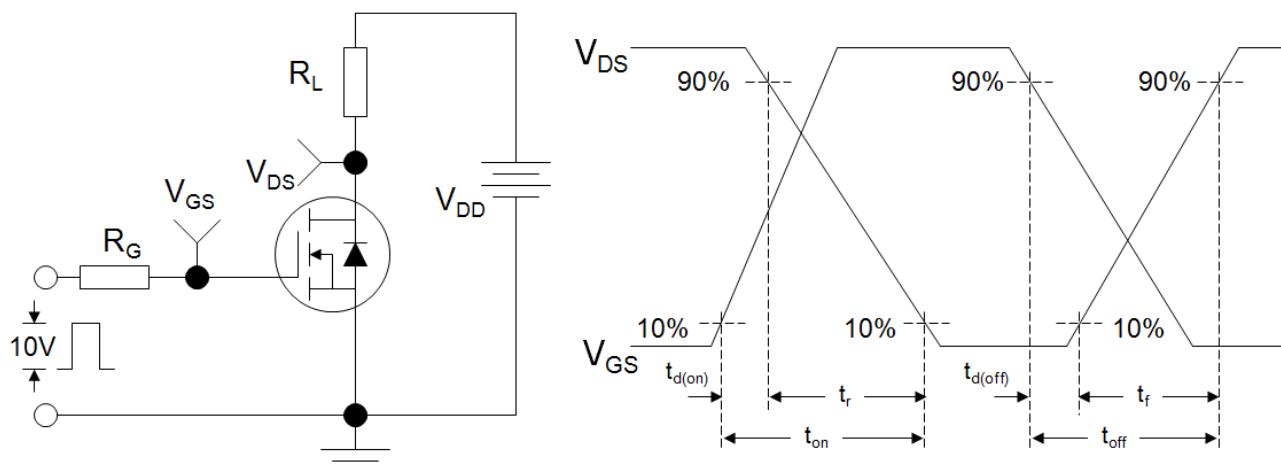
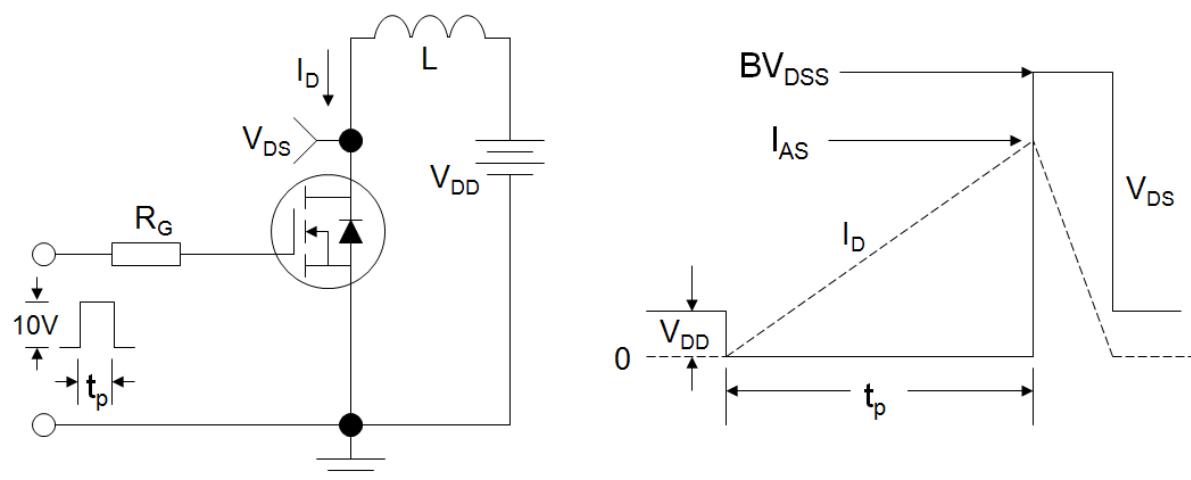
**Figure 5. Gate Charge**



**Figure 6. Body Diode Forward Voltage**



**•Typical Characteristics(Cont.)**
**Figure 7. On-Resistance vs. Junction Temperature**

**Figure 8. Breakdown voltage vs. Junction Temperature**

**Figure 9 . Transient Thermal Impedance**

**Figure 10. Safe operation area**


**•Test Circuit and Waveforms**
**Figure A: Gate Charge Test Circuit and Waveform**

**Figure B: Resistive Switching Test Circuit and Waveform**

**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**


**•Dimensions (TO-220F)**

UNIT:mm

SYMBOL	min	max	SYMBOL	min	max
A	4.20	4.80	E1	8.30	8.70
A1	2.50	2.90	e	2.40	2.70
A2	2.90	3.30	e1	4.95	5.25
b	0.40	0.80	F	2.50	2.90
b1	1.10	1.50	L	13.00	14.00
c	0.50	0.70	L1	3.00	4.00
D	9.80	10.60	ØP	2.90	3.50
E	14.60	15.60			

